



MBR230S1F

2.0A SURFACE MOUNT SCHOTTKY BARRIER RECTIFIER

Product Summary

V _{RRM} (V)	I _O (A)	V _{F(MAX)} (V) @ +25°C	I _{R(MAX)} (mA) @ +25°C	
30	2.0	0.42	1.0	

Features and Benefits

- Low Forward Voltage (V_F) Minimizes Conduction Losses and Improving Efficiency
- Guard Ring Die Construction for Transient Protection
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Description and Applications

This MBR230S1F is a single rectifier packaged in SOD123F. Ideally suited for low voltage, high frequency rectification or as free-wheeling and polarity protection diodes in surface mount applications where compact size and weight are critical to the system. Typical applications are AC-DC and DC-DC converters, reverse battery protection, and "O-ring" of multiple supply voltages and any other application where performance and size are critical.

Mechanical Data

- Case: SOD123F
- Case Material: Molded Plastic, "Green" Molding Compound UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Copper leadframe Solderable per MIL-STD-202, Method 208 (3)
- Polarity: Cathode Band
- Weight: 0.0016 grams (approximate)

SOD123F



Top View

Ordering Information (Note 4)

Part Number	Case	Packaging
MBR230S1F-7	SOD123F	3000/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html

Marking Information



F5 = Product Type Marking Code YM = Date Code Marking Y = Year (ex.: B = 2014) M = Month (ex: 9 = September)

Date Code Key

Year	2014	2015	2016	2017	2018	2019	2020	2021
Code	В	C	D	E	F	G	Н	I

Ī	Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
ĺ	Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load. For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _{RM}	30	٧
RMS Reverse Voltage	V _{R(RMS)}	21	V
Average Rectified Output Current	lo	2.0	Α
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	30	А

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Case (Note 5) Typical Thermal Resistance Junction to Ambient (Note 5)	R _{θJC} R _{θJA}	50 120	°C/W
Total Power Dissipation (Note 5)	P _{TOT}	0.84	W
Operating Temperature Range	TJ	-55 to +125	°C
Storage Temperature Range	T _{STG}	-55 to +150	°C

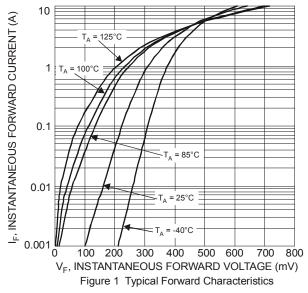
Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

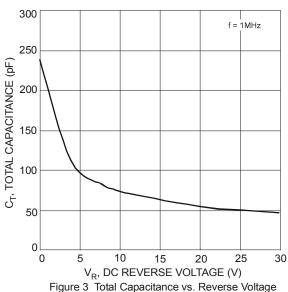
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	V _(BR)	30	_	_	V	I _R = 1.0 mA
Forward Voltage Drop	V _F	_	0.31 0.37 0.32	 0.42 	V	I _F = 1A, T _A = +25°C I _F = 2A, T _A = +25°C I _F = 2A, T _A = +100°C
Leakage Current (Note 6)	I _R	_	0.3 30	1.0 —	mA	VR = 30V, TA = +25°C VR = 30V, TA = +100°C
Total Capacitance	Ст	_	75	_	pF	VR = 10V, f = 1.0MHz

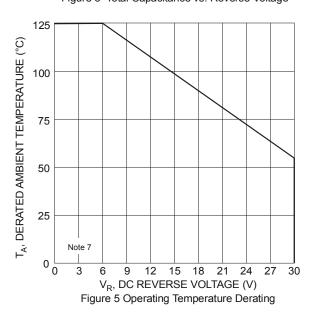
Notes:

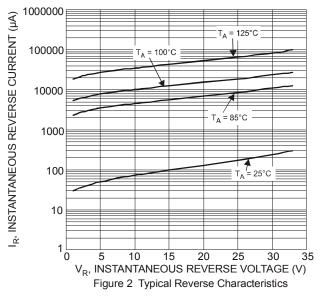
- 5. Device mounted on FR-4 substrate, 1" x 1", 2 oz, single-sided, PC boards with 0.1"*0.15" copper pad.
 6. Short duration pulse test used to minimize self-heating effect.
 7. Device mounted on FR-4 substrate, 1" x 1", 2 oz, single-sided, PC boards with minimum recommended pad per http://www.diodes.com/datasheets/ap02001.











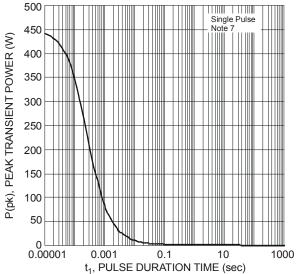
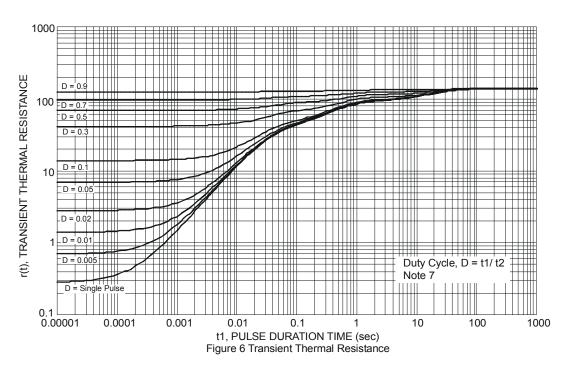


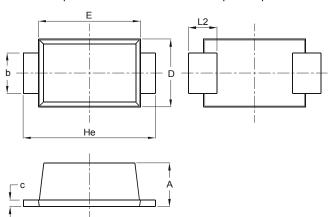
Figure 4 Single Pulse Maximum Power Dissipation





Package Outline Dimensions

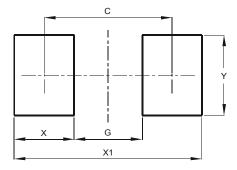
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SOD123F							
Dim	Min	Max	Тур				
Α	0.81	1.15	-				
b	0.80	1.35	-				
С	0.05	0.30	-				
D	1.70	1.90	1.80				
Е	2.60	2.80	2.70				
He	3.30	3.70	3.50				
L2	0.35	0.85	-				
All Dimensions in mm							

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for latest version.



Dimensions	Value (in mm)
С	2.86
G	1.52
Х	1.34
X1	4.20
Y	1.80



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Офис по работе с юридическими лицами:

105318, г. Москва, ул. Щербаковская д. 3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru moschip.ru_6 moschip.ru 4 moschip.ru 9